

EAST Search History

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|------|--|---|------------------|---------|------------------|
| L2 | 64 | (first upper) adj2 lead adj frame and (second lower) adj2 lead adj frame and MOSFET and (encapsulat\$4 mold\$) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/31 15:08 |
| L3 | 46 | (first upper) adj2 lead adj frame and (second lower) adj2 lead adj frame and diode adj2 (chip die ic) and (encapsulat\$4 mold\$) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/31 15:17 |
| L4 | 167 | lead adj frame and diode adj2 (chip die ic) and (encapsulat\$4 mold\$) and cathode and anode | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/31 15:20 |